

东莞市硕品电子有限公司

承 认 书

客户名称: _____

产品名称: 0.8mm Pitch 浮动板对板连接器 _____

产品料号: 66C8-FXXXXXXXXR01 66C8-MXXXXXXXXR01 _____

客户料号: _____

承认日期: _____

核准:	审核:	制作:
Lily	WLY	ZDG

客户确认			
核准	工程	品保	采购

地址: 中国广东省东莞市厚街镇白濠工业街 25 号

电话 (TEL): +86-769-83077497

传真 (FAX): +86-769-83003805

邮箱 (E-mail): sales@solepin.com

网站 (Web): www.solepin.com

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A;
- 2.2 VOLTAGE RATING: 50V.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 500MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -55°C TO +125°C.

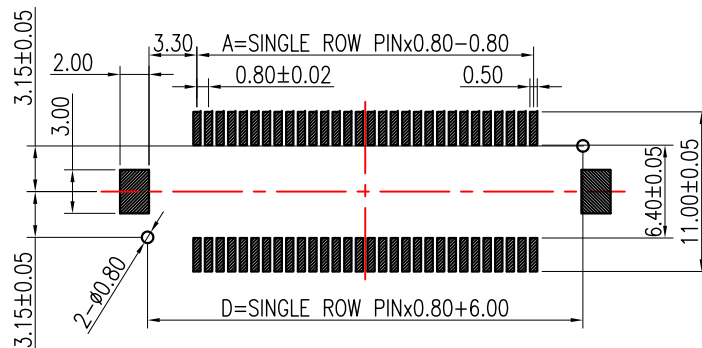
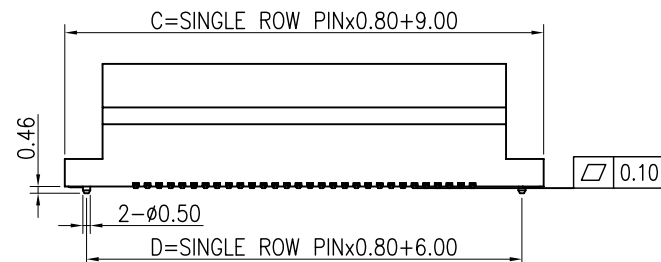
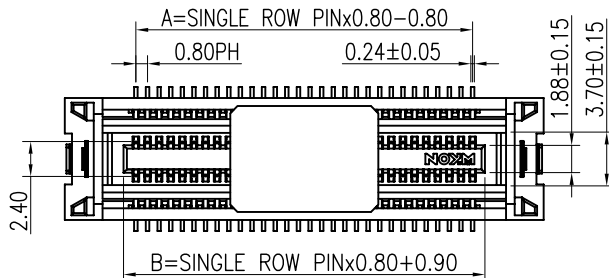
3. ORDER INFORMATION:

66C8-F XXX XX XXX R 01

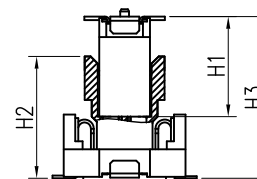
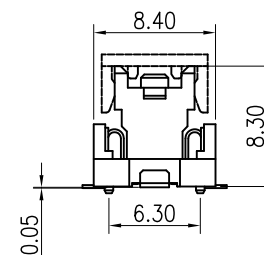
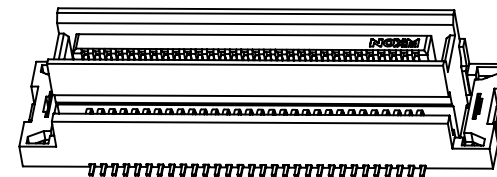
Pin 数码	端子电镀:	塑胶高度:	包装方式:
010:2x05PIN	G0=Gold Flash	049=4.90	R=TAPE REEL
.....	G1=1u" Gold	083=8.30mm	
120:2x60PIN	G2=3u" Gold		
	G3=5u" Gold		
	G4=10u" Gold		
	G5=15u" Gold		
	G6=30u" Gold		

TABLE1:

No. OF PIN	A	B	C	D
010=2x05PIN	3.20	4.90	13.00	10.00
020=2x10PIN	7.20	8.90	17.00	14.00
030=2x15PIN	11.20	12.90	21.00	18.00
040=2x20PIN	15.20	16.90	24.00	22.00
050=2x25PIN	19.20	20.90	29.00	26.00
060=2x30PIN	23.20	24.90	33.00	30.00
080=2x40PIN	31.20	32.90	41.00	38.00
100=2x50PIN	39.20	40.90	49.00	46.00
120=2x60PIN	43.20	44.90	53.00	50.00



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



MATING HEIGHT

MATING HEIGHT	H1	H2	H3
8.00mm	6.80	4.90	8.00
9.00mm	7.80		9.00
MATING HEIGHT	H1	H2	H3
11.75mm	6.80		11.75
12.75mm	7.80	8.30	12.75
18.00mm	13.05		18.00
19.50mm	14.55		19.50

					OPERATION		DRAW		Mr.Zeng		2025.09.29		SOLEPiN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD				
					X.X	±0.40	DESIGN		Jensen		2025.09.29						
					X.XX	±0.25	CHECK		Jack		2025.09.29		SIZE	A4	PART NO.	66C8-F XXX XX XXX R 01	
A0	2025.09.29	新开模		——	Mr.Zeng	X.XXX	±0.15	APPROVE				2025.09.29		SHEET	1/1	TITLE:	66C8-浮动BTB PH0.80mm 母座直立式SMT
					Angle	±3°			Andy								
REV	DATE	MODIFICATION DESCRIPTION			CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1721	

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A.
- 2.2 VOLTAGE RATING: 50V.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 500MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -55°C TO +125°C.

3. ORDER INFORMATION:

66C8-M XXX XX XXX R 01

Pin 数码
010: 2x05PIN
.....
120: 2x60PIN

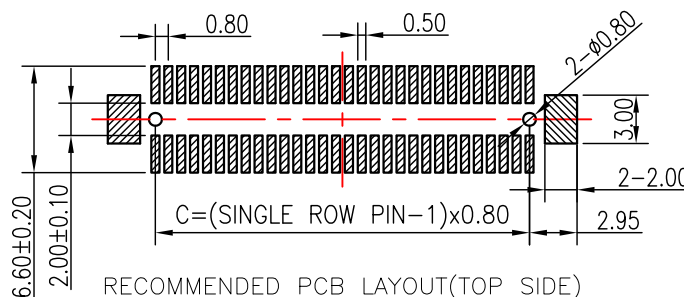
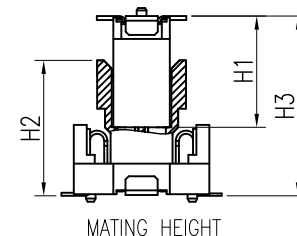
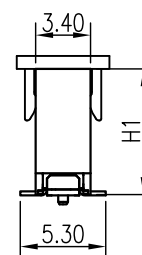
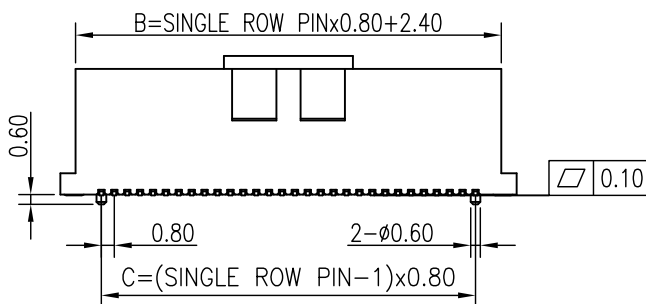
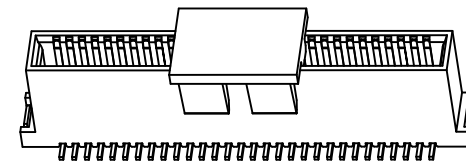
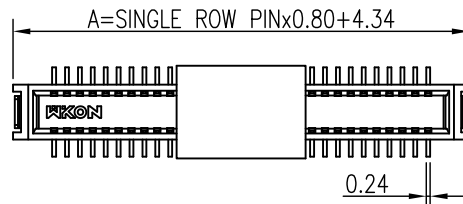
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G5=15u" Gold
G6=30u" Gold

塑胶高度:
068=6.80mm ("H1")
078=7.80mm ("H1")

包装方式:
R=TAPE REEL

TABLE1:

No. OF PIN	Dimensions		
	A	B	C
010=2*05PIN	8.34	6.40	3.20
020=2*10PIN	12.34	10.40	7.20
030=2*15PIN	16.34	14.40	11.20
040=2*20PIN	20.34	18.40	15.20
050=2*25PIN	24.30	22.40	19.20
060=2*30PIN	28.34	26.40	23.20
080=2*40PIN	36.34	34.40	31.20
100=2*50PIN	44.34	42.40	39.20
120=2*60PIN	52.34	50.40	47.20



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCE ±0.05

MATING HEIGHT

MATING HEIGHT	H1	H2	H3
8.00mm	6.80	4.90	8.00
9.00mm	7.80		9.00
MATING HEIGHT	H1	H2	H3
11.75mm	6.80	8.30	11.75
12.75mm	7.80		12.75

					OPERATION		DRAW		Mr.Zeng		2025.09.29		SOLEPIN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD.				
					X.X	±0.40	DESIGN		Jensen		2025.09.29						
					X.XX	±0.25	CHECK		Jack		2025.09.29		SIZE	A4	PART NO.	66C8-M XXX XX XXX R 01	
A0	2025.09.29	新开模		——	Mr.Zeng	X.XXX	±0.15	APPROVE		Andy		2025.09.29		SHEET	1/1	TITLE:	66C8-浮动BTB PH0.80mm 公头直立式SMT TYPE
REV	DATE	MODIFICATION DESCRIPTION		CHANGE	APPROVE	DIM.	TOL	UNIT	mm	SCALE	1:1	PROJ.		DRAW NO.	SP-1720		

客户图

NOTES:

1. FINISH:

- 1.1 HOUSING: LCP BLACK, UL94V-0.
- 1.2 CONTACT: COPPER ALLOY, GOLD (SEE P/N) PLATED IN CONTACT AREA, GOLD FLASH PLATED IN SOLDER AREA, 50u" MIN. NICKEL UNDERPLATED OVERALL.
- 1.3 GROUND: BRASS, 80u" MIN. MATTE TIN PLATED OVER 50u" MIN. NICKEL UNDERPLATED OVERALL.

2. ELECTRICAL:

- 2.1 CURRENT RATING: 0.5A.
- 2.2 VOLTAGE RATING: 50V.
- 2.3 CONTACT RESISTANCE: 120mΩ MAX.
- 2.4 INSULATION RESISTANCE: 500MΩ MIN.
- 2.5 OPERATION TEMPERATURE: -40°C TO +125°C.

3. ORDER INFORMATION:

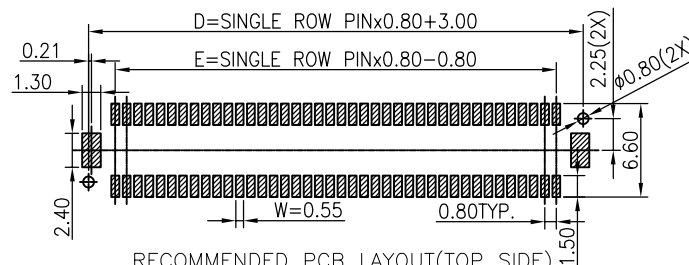
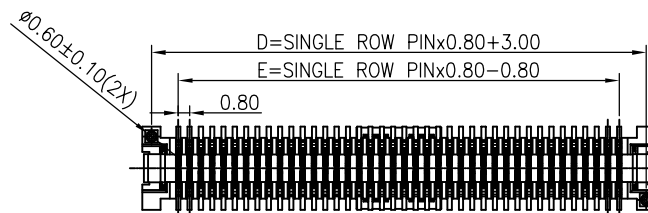
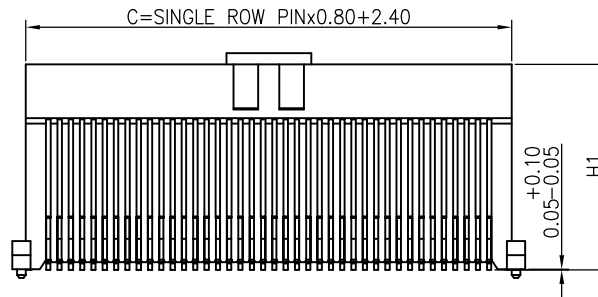
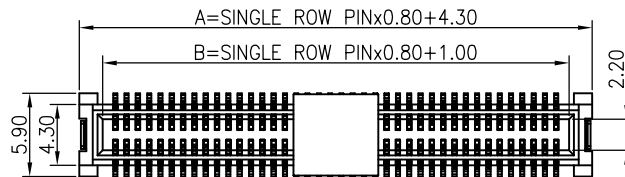
66C8-M XXX XX XXX R 01

Pin 数码
010: 2x05PIN
.....
120: 2x60PIN

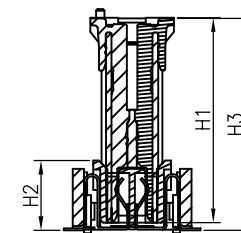
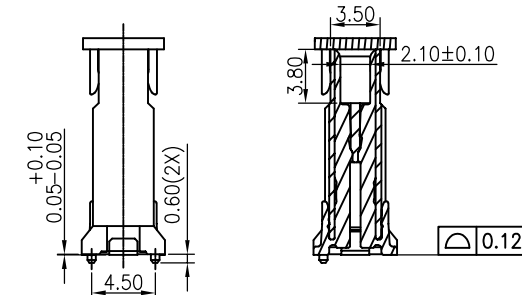
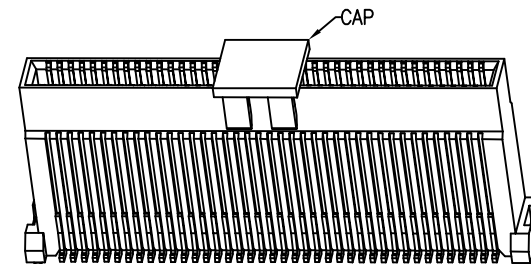
端子电镀:
G0=Gold Flash
G1=1u" Gold
G2=3u" Gold
G3=5u" Gold
G4=10u" Gold
G5=15u" Gold
G6=30u" Gold

塑胶高度:
145=14.55mm("H1")
130=13.05mm("H1")

包装方式:
R=TAPE REEL



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05



RECOMMENDED PCB LAYOUT(TOP SIDE)
PCB BOARD TOLFRANCF±0.05

MATING HEIGHT	H1	H2	H3
14.25mm	13.05	4.95	14.25
15.75mm	14.55		15.75
18.00mm	13.05	8.30	18.00
19.50mm	14.55		19.50

TABLE1:

No.OF PIN	Dimensions				
	A	B	C	D	E
010=2*05PIN	8.30	5.00	6.40	7.00	3.20
020=2*10PIN	12.30	9.00	10.40	11.00	7.20
030=2*15PIN	16.30	13.00	14.40	15.00	11.20
040=2*20PIN	20.30	17.00	18.40	19.00	15.20
050=2*25PIN	24.30	21.00	22.40	23.00	19.20
060=2*30PIN	28.30	25.00	26.40	27.00	23.20
080=2*40PIN	36.30	33.00	34.40	35.00	31.20
100=2*50PIN	44.30	41.00	42.40	43.00	39.20
120=2*60PIN	52.30	49.00	50.40	51.00	47.20

					OPERATION		DRAW		Mr.Zeng		2024.05.03		SOLEPiN 东莞市硕品电子有限公司 Professional connector manufacturer DONGGUAN SOLEPIN ELECTRONICS CO., LTD			
					X.X	±0.40	DESIGN		Jensen		2024.05.03					
					X.XX	±0.25	CHECK		Jack		2024.05.03		SIZE	A4	PART NO.	66C8—M XXX XX XXX R 01
A0		NEW			X.XXX	±0.15	APPROVE		Andy		2024.05.03		SHEET	1/1	TITLE:	浮动BTB PH0.80mm 公头直立式SMT TYPE
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	APPROVE	DIM.	TOL	UNIT		mm	SCALE	1:1	PROJ.		DRAW NO.	SP—1125	

SPECIFICATION OF PRODUCT (产品规格)

1. Scope (范围)

This product specification contains the test method, the general performance and requirement for

BTB connectors.此作业规范适用于 板对板 系列产品。

2. Applicable documents (参考文件)

Reference documents listed below shall be the latest revision unless otherwise specified.

Should a conflict occur between this specification and any of the listed documents then this specification shall prevail.

下列参考文件是最新修订版本，若本说明与其他文件有冲突时，请以本规格书为准。

2.1 Industry standards (行业标准)

EIA-364 electrical connector test procedures

EIA-364 电气连接器测试标准

MIL-STD-1344 Test Methods for Electrical Component Parts.

MIL-STD-1344 电气元件测试标准

MIL-STD-202 Test Methods for Electronic and Electrical Component Parts

MIL-STD-202 电子及电气试验方法

3. Product shape and dimensions (外观和尺寸)

Construction and physical dimensions shall be same as specified by drawings.

产品外形结构与物理尺寸请参考产品图面

4. Material And Plating (材料和电镀要求)

4.1 Material (材料)

Housing: LCP, UL94V-0; Color: BLACK

胶芯: LCP, UL94V-0 黑色

Contact: Phosphor Bronze

端子: 磷青铜

4.2 Plating (电镀)

Shell: Plated With Matte Tin Min 40u" For Allover.

铁壳: 所有表面镀雾锡最少 40u"

Contact: Plated With Gold Min 2u" For Contact Area and Plated With Matte Tin Min 80u" For Solder Area.

端子: 接触区镀金最少 2u", 焊锡区镀雾锡最少 80u"

5. Characteristics (特性)

Voltage rating: 50V AC(rms)/DC (额定电压: 50V/DC)

Current rating: 0.5A AC(rms)/DC (额定电流: 0.5A/DC)

Operating temperature range: -40°C to +105°C (操作温度: -40°C to +105°C)

Storage temperature range: -0°C to +40°C (贮存温度: -0°C to +35°C)

Storage Humidity: 10-75% RH (贮存湿度: 10-75%) Storage Time: Half a year: (贮存时间: 半年)

1. Mechanical Performance (机械特性)

Item (项目)		Test Condition (测试条件)	Requirement (要求)
1	Contact retention force 端子保持力	The end of terminal shall be pulled in a perpendicular to base housing at a maximum rate of 25 mm per minute. Test as per EIA- 364-13 端子以 25mm/分钟的速度，均速垂直于胶芯中拔出之力量。	2.9N Min.
2	Insertion Force 插入力	Measure the force necessary to insert the connector between male and female at a maximum rate of 12.5 mm per minute. Test as per EIA-364-13 (without locking lever) 公座以最大 12.5mm/分钟的速度，水平均速插入母座之力量	初期 initial 插入力 Inserted force 2.45N Max./pin
3	Unmating force 拔出力	Measure the force necessary to insert the connector between male and female at a maximum rate of 12.5 mm per minute. Test as per EIA364-13 (without locking lever) 公座以最大 12.5mm/分钟的速度，水平均速拔出母座之力量	拔去力 Extracted force 0.05N Min./pin
4	Durability 耐久	Mating and unmating the connectors for 20 cycles. Test as per EIA-364-09 公座与母座重复插入，拔出得一个循环，持续 20 个循环。	120mΩMax/ 30 times
5	Vibration 振动	Subject mated connectors to : Frequency: 10-55-10 Hz Amplitude: 1.5 mm Direction: three perpendicular axes Direction: X、Y、Z axes/2 hours Test as per EIA 364 – 28 Condition V test letter A. 振幅 1.5mm,频率 10-55-10 Hz, 在 X/Y/Z 方向各持续 2 小时	试验中无出现 1μs 以上的瞬断 试验后: 120mΩ以下 外观 Appearance 没有机械性的破损、部品 松动、裂纹等。 Discontinuity: 1μs or less After the test: 120mΩ or below No damage, loose part or crack.
6	Shock 冲击	Subject mated connectors to 30 g's half-sine shock pulses of 11ms duration. Three shocks in each direction applied along three mutually perpendicular planes for a total of 18 shocks. Test as per EIA364-27 condition H 公母座配合好后连接在 30 g's 的半正弦波冲击设备上，持续脉冲 11m,分别沿 X/Y/Z 方向共持续 18 个循环	试验中无出现 1μs 以上的瞬断 试验后: 120mΩ以下 外观 Appearance 没有机械性的破损、部品 松动、裂纹等。 Discontinuity: 1μs or less After the test: 120mΩ or below No damage, loose part or crack.

2. Electronic Performance (电气特性)

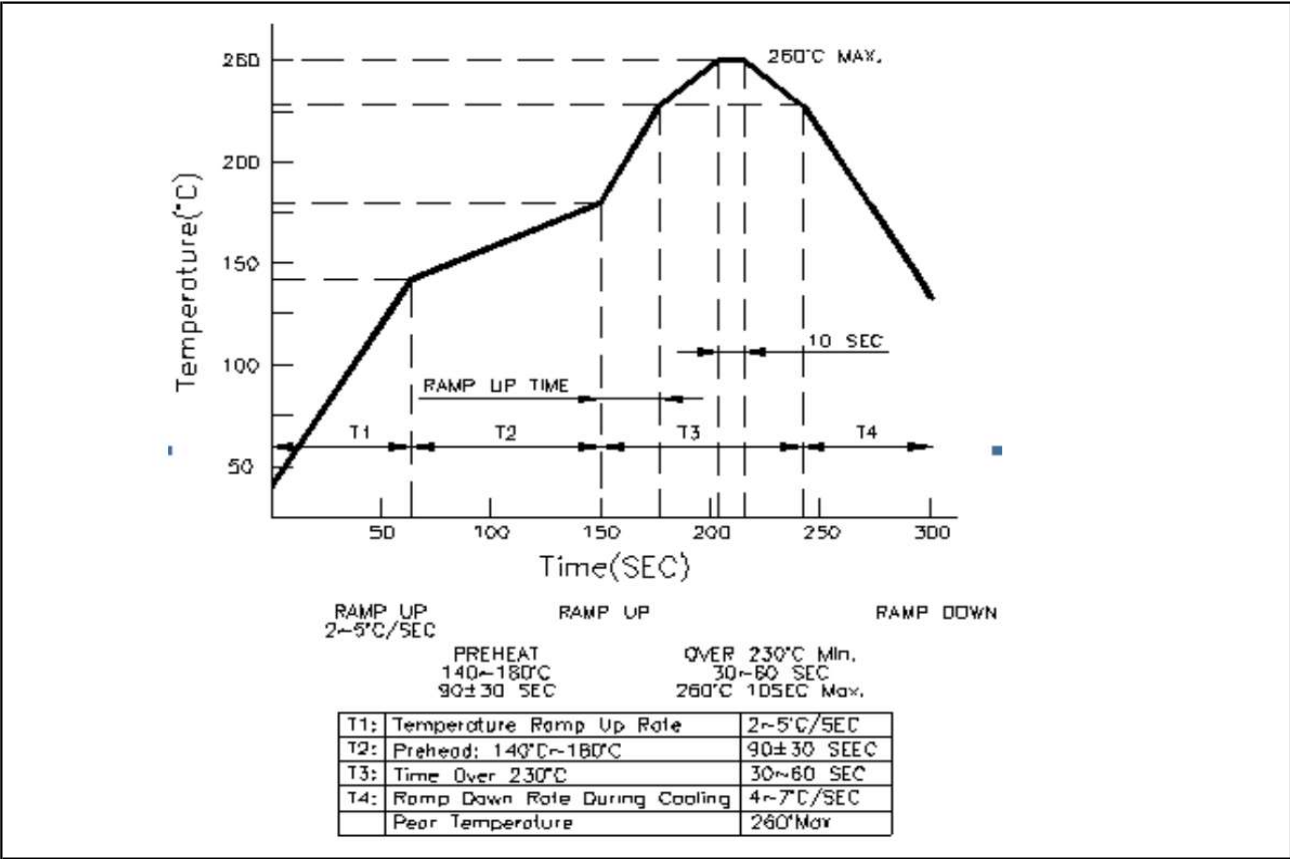
1	Dielectric withstanding voltage 耐电压	Test between adjacent contacts with a voltage of 500 V AC for 1 minute at Sea level Test as per EIA364-20 Method B 相邻端子间施加 500V AC 持续 1 分钟	No current leakage and flashover or damage detected. 无击穿, 无短路
2	Insulation resistance 绝缘阻抗	After 500V DC for 1 minute ,measure the insulation resistance between the adjacent contacts. Test as per EIA364-21 相邻端子间施加 500V DC 持续 1 分钟	500MΩ以上 (初期值) 100MΩ以上 (实验后) 500MΩ Min. (Initial) 100MΩ Min. (Final)
3	Low level Conductor resistance 接触阻抗	It shall be measured by mated, at open circuit voltage of 20mV Max, 1mA . 嵌合状态下, 开路电压 20mV 以下, 1mA	100mΩ以下 (初期) 120mΩ以下 (各试验后) 100mΩ Max. (Initial) 120mΩ Max. (Final)

3.Environmental Performance (环境特性)

1	Temperature life high 耐高温	The connector mated is exposed in the heat chamber 105±2 °C for 96 hours. It shall be measured the contact resistance after the test.公母座嵌合状态下, 放置于 105±2°C环境中 96 小时。测量试验后的接触电阻。	120mΩ Max.
2	Humidity 耐湿性	The connector mated is exposed in the humidity chamber 60 ± 2°C,90~95%RH for 96 hours. It shall be measured the contact resistance after the test. 公母座嵌合状态下, 放置于 60±2°C、	120mΩ Max.
3	Cold resistance 耐寒性	The connector mated is exposed in the heat chamber -40±2 °C for 96 hours. It shall be measured the contact resistance after the test. 公母座嵌合状态下, 放置于-40±2°C环境中 96 小时。测量试验后的接触电阻。	120mΩ Max.
4	Salt spray test 盐水喷雾试验	The connector mated is exposed in the salt spray chamber 35±2°C,5±1 saltdensity for 48 hours. It shall be measured the contact resistance after the test. 公母座嵌合状态下, 放置于 35±2°C、浓度 5±1%的盐水喷雾中 48 小时。取出之后使用纯水清洗, 干燥后测量接触电阻。	120mΩ Max.
5	SO2 gas test SO2 气体实验	The connector mated is exposed in the SO2 gas chamber 40 ± 2°C,75%RH 、10±3ppm for 96 hours. It shall be measured the contact resistance after the test. 公母座嵌合状态下, 放置于 40±2°C、相对湿度 75%RH、SO2 浓度 10±3ppm的环境中 96 小时。测量试验后的接触电阻。	120mΩ Max.
6	H2S gas test H2S 气体实验	The connector mated is exposed in the H2S gas chamber 40 ± 2°C,75%RH 、3±1ppm for 96 hours. It shall be measured the contact resistance after the test. 公母座嵌合状态下, 放置于 40±2°C、相对湿度 75%RH、H2S 浓度 3±1ppm 的环境中 96 小时。测量试验后的接触电阻。	120mΩ Max.

7	Thermal shock test 冷热冲击试验	subject unmated connectors shall be tested in accordance with EIA364-32 Test Condition I . -55±2°C(30 minute) →+25±2°C(5 minute) →+85±2°C(30 minute) →+25±2°C(5 minute) consecutive 5 cycles. 适配板对板连接器，环境温度-55±2°C(30 minute) →+25±2°C(5 minute) →+85±2°C(30 minute) →+25±2°C(5 minute) 持续 5 个循环。	120mΩ Max.
8	Humidity resistance 恒温恒湿	Subject unmated connectors to 96 hours at 60°C with 90% to 95% R.H. Test as per EIA 364 – 31 Method II Test Condition A. 环境温度 60°C，湿度 90% ~ 95% R.H，持续时间 96H。	120mΩ Max.
9	Solder ability 焊锡性	Immersion in Flux consisting rosin 10% and methanol 90% for a period of 5 to10 seconds dip in molten solder consisting of Sn-Ag-Cu at 260°C plus or minus 5 degree for 3 plus or minus 0.5 seconds. 产品焊锡区在松香 10%和甲醇 90%的助焊剂中浸泡 5-10 秒，再将焊锡区浸入 260°C 的焊料中持续 3 秒。	More than 95% of area dipped in molten solder should be coated by solder 焊锡区吃锡饱满度95%以上

4. Recommended Temperature Profile (推荐温度曲线)



NOTE (备注)

SMT stencil thickness: Pin solder area 0.12 ~ 0.15mm, shell solder area 0.15 ~ 0.18mm
SMT 钢网厚度: Pin 针焊锡区 0.12 ~ 0.15mm, 铁壳焊锡区 0.15 ~ 0.18mm

5.Attention of using /使用注意事项

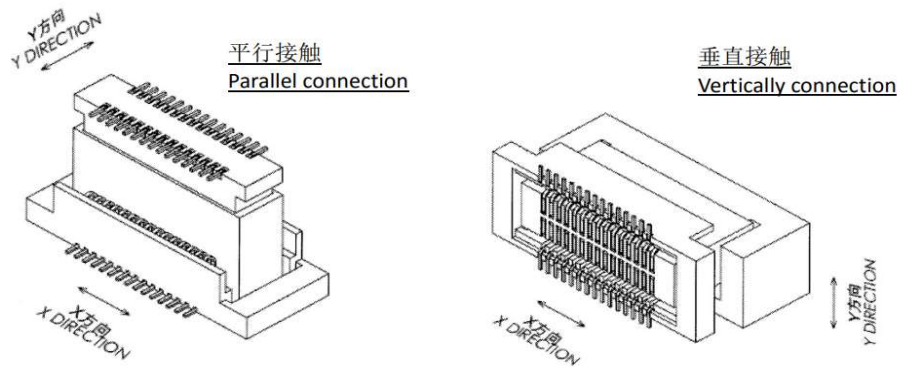
1.浮动量/Floating Range

本规格书所限定浮动板对板产品，在嵌合状态下允许浮动范围:

The floating range of the following

① X 方向浮动量/X Direction:±0.5mm

② Y 方向浮动量/Y Direction:±0.5mm



※注意：使用过程中请勿超出所允许的浮动量！

Note: Do not exceed the allowed floating range during use!

2. 使用时的注意事项/Attention of using connector

· 请缓慢插接，请勿斜着或扭上劲进行插接连接器。

/When the connector is mating, shall not be twisted, and then mated it slowly.

· 斜着插接，壳体之间产生摩擦，会产生摩擦粉

/The angled mating, occurs shavings.

· 找到对接位置，确认壳体接口之间是否到位后，缓慢进行插接

/After positioning, please check that mold both ends have fitted in loosely, and push in straight.

· 拔取时保持平行，请勿单边拔取连接器而产生回转，以免造成壳体的损坏。

/Please be pulled out straight. Pulling on one side, the mold is broken.

· 以下视图仅作为参考。（可能会与实物有所不同）

/It refers to the model shape of the reference of the following.

(It differs from a actual connector.)

· 请勿将连接器作为电路板之间的固定使用。必须在连接器实装位置的附近，用螺丝等确实有效的固定电路板。

对于组装件，连接器受到的加速度应小于 43.12 m/s^2

。（不能有共振现象）

/It shall not be held the connector only, when you are assembled for the connector and P.C.B.

When it shall be used the connector, the P.C.B. are held by the rivet certainty near mounting of the connector.

Acceleration of connector $\leq 43.12 \text{ m/s}^2$

or less. (The connector shall not be added to be added to resonance acceleration.)

建议
使用定位导向装置。如果在切合位置不佳的状态下插接使用，会造成连接器的损坏或变形。找到对接位置，确认壳体切合口到

位后，

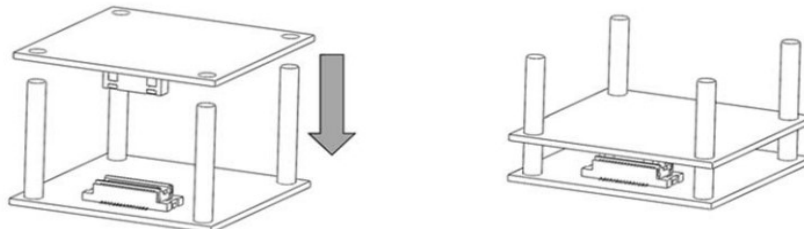
缓慢插接连接器。

/ It is recommended to engage with a jig that guides the position.

If it is pushed in a state where the mating position is displaced, there is a possibility of damage or deformation.

After positioning, please check that mold both ends have fitted in loosely, and push in straight.

(例 / Example)



· 定位导向角度如图 1 至图 2 所示，请在图示角度以下进行插接连接器。

Figure 1 and 2 show guiding angle. Please locate it below the described angle.

（定位导向角度是最初定位角度，而不是可以插接连接器的角度。）

(Guiding angle is initial location angle. It is not the angle to mate.)

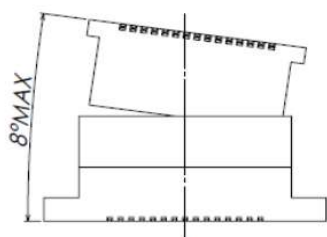


图 1/ Fig.1(平行对接型/Parallel connection type)

导向角度
Guiding angle

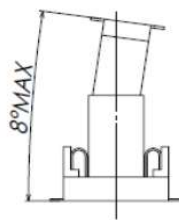


图 2/ Fig.2(平行对接型/ Parallel connection type)

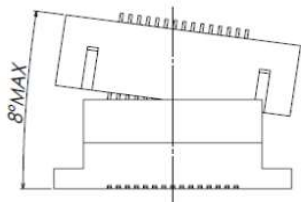


图 1/ Fig.1(垂直对接型/Vertical connection type)

导向角度
Guiding angle

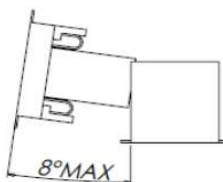


图 2/ Fig.2(垂直对接型/ Vertical connection type)

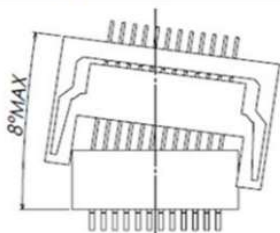


图 1/ Fig.1(水平对接型/Horizontal connection type)

导向角度
Guiding angle

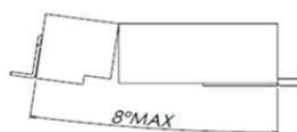


图 2/ Fig.2(水平对接型/Horizontal connection type)

· 图 3 及图 4 表示对接时的最大角度，请在记载角度以下进行对接。
Please mate below the angle of the figure 3,4.

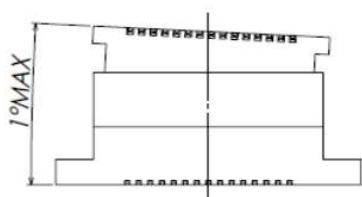


图 3/ Fig.3(平行对接型/Parallel connection type)

插接角度
Mating angle

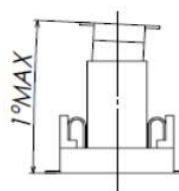


图 3/ Fig.3(平行对接型/ Parallel connection type)

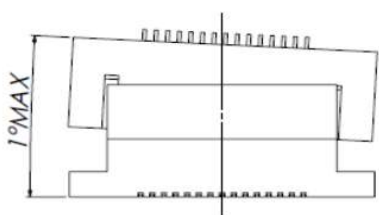


图 3/ Fig.3(垂直对接型/Vertical connection type)

插接角度
Mating angle



图 4/ Fig.4(垂直对接型/ Vertical connection type)

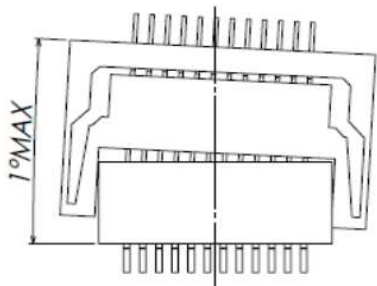


图 3/ Fig.3(水平对接型/Horizontal connection type)

插接角度
Mating angle

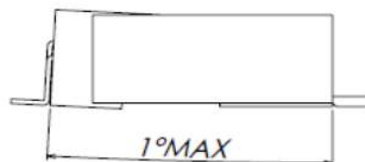


图 4/ Fig.4(水平对接型/Horizontal connection type)